

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

General Description

The MAX5723/MAX5724/MAX5725 8-channel, low-power, 8-/10-/12-bit, voltage-output digital-to-analog converters (DACs) include output buffers and an internal 3ppm/°C reference that is selectable to be 2.048V, 2.500V, or 4.096V. The MAX5723/MAX5724/MAX5725 accept a wide supply voltage range of 2.7V to 5.5V with extremely low power (6mW) consumption to accommodate most low-voltage applications. A precision external reference input allows rail-to-rail operation and presents a 100k Ω (typ) load to an external reference.

The MAX5723/MAX5724/MAX5725 have a fast 50MHz, 4-wire SPI/QSPI™/MICROWIRE®/DSP-compatible serial interface that operates at clock rates up to 50MHz. The DAC output is buffered and has a low supply current of less than 250µA per channel and a low offset error of ±0.5mV (typ). On power-up, the MAX5723/MAX5724/ MAX5725 reset the DAC outputs to zero or midscale based on the status of M/Z logic input, providing flexibility for a variety of control applications. The internal reference is initially powered down to allow use of an external reference. The MAX5723/MAX5724/MAX5725 allow simultaneous output updates using software LOAD commands or the hardware load DAC logic input (LDAC).

The MAX5723/MAX5724/MAX5725 feature a programmable watchdog function which can be enabled to monitor the I/O interface for activity and integrity.

A clear logic input (CLR) allows the contents of the CODE and the DAC registers to be cleared asynchronously and simultaneously sets the DAC outputs to the programmable default value. The MAX5723/MAX5724/MAX5725 are available in a 20-pin TSSOP and an ultra-small, 20-bump WLP package and are specified over the -40°C to +125°C temperature range.

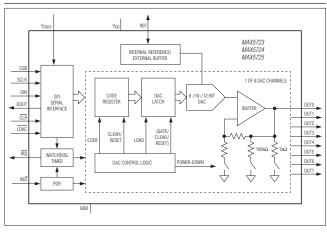
Applications

Programmable Voltage and Current Sources Gain and Offset Adjustment Automatic Tuning and Optical Control Power Amplifier Control and Biasing Process Control and Servo Loops Portable Instrumentation

QSPI is a trademark of Motorola, Inc. MICROWIRE is a registered trademark of National Semiconductor Corporation. µMAX is a registered trademark of Maxim Integrated Products, Inc.

Benefits and Features

- Eight High-Accuracy DAC Channels
 12-Bit Accuracy Without Adjustment
 - ♦ ±1 LSB INL Buffered Voltage Output
 - ♦ Guaranteed Monotonic Over All Operating Conditions
 - \diamond Independent Mode Settings for Each DAC
- ♦ Internal Output Buffer
 ♦ Rail-to-Rail Operation with External Reference
 ♦ 4.5µs Settling Time
 - \diamond Outputs Directly Drive 2k Ω Loads
- Small 6.5mm x 4.4mm 20-Pin TSSOP or Ultra-Small 2.5mm x 2.3mm 20-Bump WLP Package
- Wide 2.7V to 5.5V Supply Range
- ♦ Separate 1.8V to 5.5V V_{DDIO} Power-Supply Input
- Fast 50MHz 4-Wire SPI/QSPI/MICROWIRE/DSP-Compatible Serial Interface
- Programmable Interface Watchdog Timer
- Pin-Selectable Power-On-Reset to Zero-Scale or Midscale DAC Output
- ◆ **LDAC** and **CLR** For Asynchronous DAC Control



Functional Diagram

Ordering Information appears at end of data sheet.

For related parts and recommended products to use with this part, refer to: www.maximintegrated.com/MAX5723.related

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maximintegrated.com.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ABSOLUTE MAXIMUM RATINGS

 $\label{eq:VDD} \begin{array}{l} V_{DD,} V_{DDIO} \mbox{ to GND } -0.3V \mbox{ to +6V } \\ OUT_, \mbox{ REF to GND} 0.3V \mbox{ to the lower of } (V_{DD} + 0.3V) \mbox{ and +6V } \\ SCLK, \mbox{ CSB, } \overline{IRQ}, \mbox{ M/Z}, \mbox{ LDAC, } \overline{CLR} \mbox{ to GND} -0.3V \mbox{ to +6V } \\ DIN, \mbox{ DOUT to GND } -0.3V \mbox{ to the lower of } \\ (V_{DDIO} + 0.3V) \mbox{ and +6V } \\ Continuous \mbox{ Power Dissipation } (T_A = +70^\circ\text{C}) \\ \mbox{ TSSOP (derate at 13.6mW/^{\circ}\text{C above } 70^\circ\text{C})..... 1084mW } \\ WLP \mbox{ (derate at 21.3mW/^{\circ}\text{C above } 70^\circ\text{C})..... 1700mW } \end{array}$

 Maximum Continuous Current into Any Pin
 ±50mA

 Operating Temperature
 -40°C to +125°C

 Storage Temperature
 -65°C to +150°C

 Lead Temperature (TSSOP only)(soldering, 10s)
 +300°C

 Soldering Temperature (reflow)
 +260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

TSSOPWLPJunction-to-Ambient Thermal Resistance (θ_{JA})73.8°C/WJunction-to-Ambient ThermJunction-to-Case Thermal Resistance (θ_{JC})20°C/W(Note 2)

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <u>www.maximintegrated.com/thermal-tutorial</u>.

Note 2: Visit <u>www.maximintegrated.com/app-notes/index.mvp/id/1891</u> for information about the thermal performance of WLP packaging.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = 2.7V \text{ to } 5.5V, V_{DDIO} = 1.8V \text{ to } 5.5V, V_{GND} = 0V, C_L = 200\text{pF}, R_L = 2k\Omega, T_A = -40^{\circ}\text{C}$ to +125°C, unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC PERFORMANCE (Note 4)						
		MAX5723	8			
Resolution and Monotonicity	Ν	MAX5724	10			Bits
		MAX5725	12			
		MAX5723	-0.25	±0.05	+0.25	
Integral Nonlinearity (Note 5)	INL	MAX5724	-0.5	±0.2	+0.5	LSB
		MAX5725	-1	±0.5	+1	
		MAX5723	-0.25	±0.05	+0.25	
Differential Nonlinearity (Note 5)	DNL	MAX5724	-0.5	±0.1	+0.5	LSB
		MAX5725	-1	±0.2	+1	
Offset Error (Note 6)	OE		-5	±0.5	+5	mV
Offset Error Drift				±10		µV/°C
Gain Error (Note 6)	GE		-1.0	±0.1	+1.0	%FS
Gain Temperature Coefficient		With respect to V _{REF}		±3.0		ppm of FS/°C

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	C	ONDITIONS	MIN	TYP	MAX	UNITS
Zero-Scale Error				0		+10	mV
Full-Scale Error		With respect to \	/ _{REF}	-0.5		+0.5	%FS
DAC OUTPUT CHARACTERIST	ICS						
		No load		0		V _{DD}	
Output Voltage Range (Note 7)		2k Ω load to GNE)	0		V _{DD} - 0.2	V
		2k Ω load to V _{DD}		0.2		V _{DD}	
			$V_{DD} = 3V \pm 10\%,$ $II_{OUT}I \le 5mA$		300		
Load Regulation		$V_{OUT} = V_{FS}/2$	$V_{DD} = 5V \pm 10\%,$ $II_{OUT}I \le 10mA$		300		μV/mA
			$V_{DD} = 3V \pm 10\%,$ $II_{OUT}I \le 5mA$		0.3		Ω
DC Output Impedance		$V_{OUT} = V_{FS}/2$	$V_{DD} = 5V \pm 10\%,$ $II_{OUT}I \le 10mA$		0.3		52
Maximum Capacitive Load Handling	CL				500		pF
Resistive Load Handling	RL			2			kΩ
Short Circuit Output Current			Sourcing (output shorted to GND)		30		
Short-Circuit Output Current		$V_{DD} = 5.5V$	Sinking (output shorted to V_{DD})		50		mA
DC Power-Supply Rejection		$V_{DD} = 3V \pm 10\%$	or 5V ±10%		100		μV/V
DYNAMIC PERFORMANCE							
Voltage-Output Slew Rate	SR	Positive and neg	ative		1.0		V/µs
		¹ ⁄ ₄ scale to ³ ⁄ ₄ sca	ale, to \leq 1 LSB, MAX5723		2.2		
Voltage-Output Settling Time		¹ ⁄ ₄ scale to ³ ⁄ ₄ sca	ale, to \leq 1 LSB, MAX5724		2.6		μs
		1/4 scale to 3/4 sca	ale, to \leq 1 LSB, MAX5725		4.5		
DAC Glitch Impulse		Major code trans	sition (code x7FF to x800)		7		nV*s
Channel-to-Channel		Internal referenc	e		3.3		1.14
Feedthrough (Note 8)		External reference	ce		4.07		nV*s
Digital Feedthrough		Midscale code, a	all digital inputs from 0V to		0.2		nV*s
Devuer I las Tires e		Startup calibratio	on time (Note 9)		200		μs
Power-Up Time		From power-dow	/n		50		μs

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CON	IDITIONS	MIN	TYP	MAX	UNITS
			f = 1kHz		90		
		External reference	f = 10kHz		82		1
		2.048V internal	f = 1kHz		112]
Output Voltage-Noise Density		reference	f = 10kHz		102]
(DAC Output at Midscale)		2.5V internal	f = 1kHz		125		- nV/√Hz
		reference	f = 10kHz		110		1
		4.096V internal	f = 1kHz		160]
		reference	f = 10kHz		145		1
			f = 0.1Hz to 10Hz		12		
		External reference	f = 0.1Hz to $10kHz$		76		1
			f = 0.1Hz to 300kHz		385	·]
			f = 0.1Hz to 10Hz		14		1
		2.048V internal	f = 0.1Hz to $10kHz$		91]
Integrated Output Noise		reference	f = 0.1Hz to 300kHz		450] .,
(DAC Output at Midscale)			f = 0.1Hz to 10Hz		15		μV _{P-P}
		2.5V internal	f = 0.1Hz to 10kHz		99]
		reference	f = 0.1Hz to 300kHz		470]
			f = 0.1Hz to 10Hz		16]
		4.096V internal	f = 0.1Hz to $10kHz$		124		1
		reference	f = 0.1Hz to 300kHz		490]
			f = 1kHz		114		
		External reference	f = 10kHz		99]
		2.048V internal	f = 1kHz		175		
Output Voltage-Noise Density		reference	f = 10 kHz		153		
(DAC Output at Full Scale)		2.5V internal	f = 1kHz		200		nV/√Hz
		reference	f = 10 kHz		174		
		4.096V internal	f = 1kHz		295		
		reference	f = 10kHz		255]
			f = 0.1Hz to 10Hz		13		
		External reference	f = 0.1Hz to $10kHz$		94		
			f = 0.1Hz to 300kHz		540]
			f = 0.1Hz to 10Hz		19		1
		2.048V internal	f = 0.1Hz to $10kHz$		143		
Integrated Output Noise		reference	f = 0.1Hz to 300kHz		685		
(DAC Output at Full Scale)			f = 0.1Hz to 10Hz		21		μν _{Ρ-Ρ}
		2.5V internal	f = 0.1Hz to $10kHz$		159]
		reference	f = 0.1Hz to 300kHz		705]
			f = 0.1Hz to 10Hz		26]
		4.096V internal	f = 0.1Hz to $10kHz$		213]
		reference	f = 0.1Hz to 300kHz		750		1

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CONE	DITIONS	MIN	ТҮР	MAX	UNITS
REFERENCE INPUT		L					
Reference Input Range	V _{REF}			1.24		V _{DD}	V
Reference Input Current	I _{REF}	$V_{\text{REF}} = V_{\text{DD}} = 5.5 \text{V}$			55	74	μA
Reference Input Impedance	R _{REF}			75	100		kΩ
REFERENCE OUTPUT		.1		1			1
		V _{REF} = 2.048V, T _A =	: +25°C	2.043	2.048	2.053	
Reference Output Voltage	V _{REF}	$V_{\text{REF}} = 2.5 \text{V}, \text{T}_{\text{A}} = +$	25°C	2.494	2.500	2.506	V
		V _{REF} = 4.096V, T _A =	: +25°C	4.086	4.096	4.106	
Reference Temperature		MAX5725A			±3	±10	ppm/°C
Coefficient (Note 10)		MAX5723/MAX5724	/MAX5725B		±10	±25	ppm/°C
Reference Drive Capacity		External load			25		kΩ
Reference Capacitive Load Handling					200		pF
Reference Load Regulation		$I_{\text{SOURCE}} = 0 \text{ to } 500 \mu$	AL		2	·	mV/mA
Reference Line Regulation					0.05		mV/V
POWER REQUIREMENTS	1						
		$V_{REF} = 4.096V$		4.5		5.5	
Supply Voltage	V _{DD}	All other options		2.7		5.5	- V
I/O Supply Voltage	V _{DDIO}			1.8		5.5	V
			$V_{REF} = 2.048V$		1.6	2	1
		Internal reference	$V_{\text{REF}} = 2.5V$		1.7	2.1	1
Supply Current (Note 11)	I _{DD}		$V_{\rm RFF} = 4.096V$		2.0	2.5	mA
			$V_{\text{REF}} = 3V$		1.6	2.0	1
		External reference	$V_{\text{REF}} = 5V$		1.9	2.5	1
		All DACs off, interna		_	140		1
Power-Down Mode Supply	I _{PD}	All DACs off, interna $T_A = -40^{\circ}C$ to $+85^{\circ}C$	l reference OFF,		0.7	2	μA
Current		All DACs off, interna $T_A = +125^{\circ}C$			2	4	
Digital Supply Current	I _{DDIO}	Static logic inputs, a	Il outputs unloaded			1	μA
DIGITAL INPUT CHARACTER				1			· · ·
Input Leakage Current	I _{IN}	· · · · · · · · · · · · · · · · · · ·	all inputs except M/\overline{Z}		±0.1	±1	μA
		$V_{IN} = 0V \text{ or } V_{DD}, \text{ for}$	M/Z (Note 11)				

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CON	DITIONS	MIN	ТҮР	MAX	UNITS
		(All inputs except	2.2V < V _{DDIO} < 5.5V	0.7 x V _{DDIO}			V
Input High Voltage	V _{IH}	M/\overline{Z})	1.8V < V _{DDIO} < 2.2V	0.8 x V _{DDIO}			
		2.7V < V _{DD} < 5.5V	(for M/\overline{Z})	0.7 x V _{DD}			V
		(All inputs except	2.2V < V _{DDIO} < 5.5V			0.3 x V _{DDIO}	V
Input Low Voltage	VIL	M/Z)	1.8V < V _{DDIO} < 2.2V			0.2 x V _{DDIO}	V
		$2.7V < V_{DD} < 5.5V$	(for M/\overline{Z})			0.3 x V _{DD}	v
Input Capacitance (Note 10)	CIN					10	pF
Hysteresis Voltage	V _H				0.15		V
DIGITAL OUTPUT (IRQ)	1						
Output Low Voltage	V _{OL}	I _{SINK} = 3mA				0.2	V
Output Inactive Leakage	I _{OFF}				±0.1	±1	μA
Output Inactive Capacitance (Note 10)	C _{OFF}					10	pF
DIGITAL OUTPUT (DOUT)				·			
Output Ligh Voltage		V _{DDIO} > 2.5V, I _{SOL}	JRCE = 3mA	V _{DDIO} - 0.2			V
Output High Voltage	V _{OH}	V _{DDIO} > 1.8V, I _{SOL}	JRCE = 2mA	V _{DDIO} - 0.2			V
Output Low Voltage	V _{OL}	$V_{\text{DDIO}} > 2.5 \text{V}, I_{\text{SINF}}$	x = 3mA			0.2	V
Output Low Voltage	VOL	V _{DDIO} > 1.8V, I _{SIN}	$\chi = 2mA$			0.2	· ·
Output Short-Circuit Current	I _{OSS}	ISINK, ISOURCE			±100		mA
Output Three-State Leakage	I _{OZ}				±0.1	±1	μA
Output Three-State Capacitance	C _{OZ}				10		pF
WATCHDOG TIMER CHARACT	ERISTICS	1					
Watchdog Timer Period	twdosc	$V_{DD} = 3V, T_A = +28$	5°C	0.95	1	1.05	ms
Watchdog Timer Period Supply Drift		$V_{DD} = 2.7V \text{ to } 5.5V$, T _A = +25°C		0.6		%/V
Watchdog Timer Period Temperature Drift		$V_{DD} = 3V$			0.0375		%/°C

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CONE	DITIONS	MIN	ТҮР	MAX	UNITS
SPI TIMING CHARACTERISTIC	S						
			Write mode	0		50	
		2.7V < V _{DDIO} < 5.5V	Read mode, strobing on 1 SCLK	0		25	
2011/ 5	r.		Read mode, strobing on ½ SCLK	0		12.5	
SCLK Frequency	^f SCLK		Write mode	0		33	MHz
		1.8V < V _{DDIO} < 2.7V	Read mode, strobing on 1 SCLK	0		20	
			Read mode, strobing on ½ SCLK	0		10	
SCLK Period	taaruu	2.7V < V _{DDIO} < 5.5V	, write mode	20			
SOLK Fellou	^t SCLK	1.8V < V _{DDIO} < 2.7V	, write mode	30			ns
SCLK Pulse Width High	t _{CH}			8			ns
SCLK Pulse Width Low	t _{CL}			8			ns
CSB Fall to SCLK Fall Setup Time	+	To first SCLK falling	$2.7\mathrm{V} < \mathrm{V}_\mathrm{DDIO} < 5.5\mathrm{V}$	8			
CSB Fail to SOLK Fail Setup Time	tCSSO	edge	$1.8\mathrm{V} < \mathrm{V}_\mathrm{DDIO} < 2.7\mathrm{V}$	12			ns
CSB Fall to SCLK Fall Hold Time	t _{CSH0}	Applies to inactive SC preceding the first SC		0			ns
CSB Rise to SCLK Fall Hold Time	t _{CSH1}	Applies to the 24th S	CLK falling edge	0			ns
CSB Rise to SCLK Fall	t _{CSA}	Applies to the 24th SC aborted sequence	CLK falling edge,	12			ns
SCLK Fall to CSB Fall	tCSF	Applies to 24th SCL	K falling edge	100			ns
CSB Pulse Width High	tCSPW			20			ns
DIN to SCLK Fall Setup Time	t _{DS}			5			ns
DIN to SCLK Fall Hold Time	t _{DH}			4.5			ns
CLR Pulse Width Low	t _{CLPW}			20			ns
CLR Rise to CSB Fall	tcsc	Required for comma	nd to be executed	20			ns
LDAC Pulse Width Low	t _{LDPW}			20			ns
LDAC Fall to SCLK Fall Hold	tLDH	Applies to 24th SCLK	falling edge	20			ns
		DPHA = 0,	2.7V < V _{DDIO} < 5.5V			35	
SCLK Fall to DOUT Transition	t _{DOT}	$C_{LOAD} = 20 pF$	1.8V < V _{DDIO} < 2.7V			40	ns
		DPHA = 1,	2.7V < V _{DDIO} < 5.5V			35	
SCLK Rise to DOUT Transition	^t DOT	$C_{LOAD} = 20 pF$	1.8V < V _{DDIO} < 2.7V			40	ns

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

ELECTRICAL CHARACTERISTICS (continued)

(V_{DD} = 2.7V to 5.5V, V_{DDIO} = 1.8V to 5.5V, V_{GND} = 0V, C_L = 200pF, R_L = 2k Ω , T_A = -40°C to +125°C, unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CON	DITIONS	MIN	ТҮР	MAX	UNITS
SCLK Fall to DOUT Hold	t _{DOH}	DPHA = 0, C _{LOAD} =	= 0pF	2			ns
SCLK Rise to DOUT Hold	t _{DOH}	DPHA = 1, C_{LOAD} =	= 0pF	2			ns
CSB Fall to DOUT Fall	t _{DOE}	Enable time, C _{LOAD}) = 20pF			20	ns
			2.7V < V _{DDIO} < 5.5V			20	
CSB Rise to DOUT Hi-Z	tDOZ	Disable time	1.8V < V _{DDIO} < 2.7V			40	ns

Note 3: Electrical specifications are production tested at $T_A = +25$ °C. Specifications over the entire operating temperature range are guaranteed by design and characterization. Typical specifications are at $T_A = +25$ °C.

Note 4: DC performance is tested without load, $V_{REF} = V_{DD}$.

Note 5: Linearity is tested with unloaded outputs to within 20mV of GND and V_{DD} .

Note 6: Gain and offset calculated from measurements made with $V_{REF} = V_{DD}$ at codes 30 and 4065 for MAX5725, codes 8 and 1016 for MAX5724, and codes 2 and 254 for MAX5723.

Note 7: Subject to zero- and full-scale error limits and V_{REF} settings.

Note 8: Measured with all other DAC outputs at midscale with one channel transitioning 0 to full scale.

Note 9: On power-up, the device initiates an internal 200µs (typ) calibration sequence. All commands issued during this time will be ignored.

Note 10: Guaranteed by design.

Note 11: All channels active at V_{FS} , unloaded. Static logic inputs with $V_{IL} = V_{GND}$ and $V_{IH} = V_{DDIO}$ for all inputs.

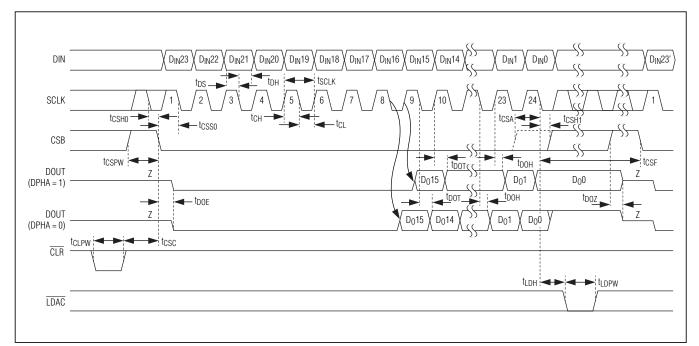
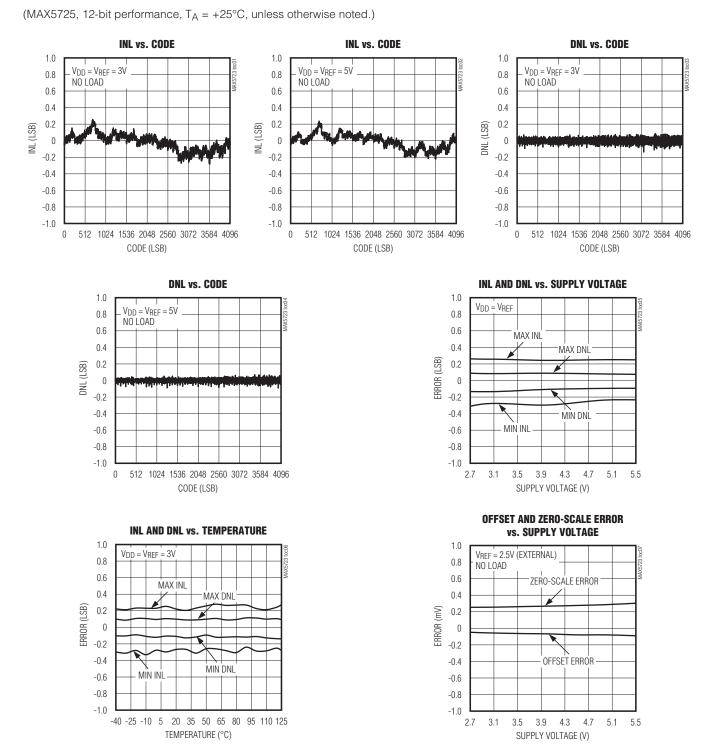


Figure 1. SPI Serial Interface Timing Diagram

MAX5723/MAX5724/MAX5725 Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

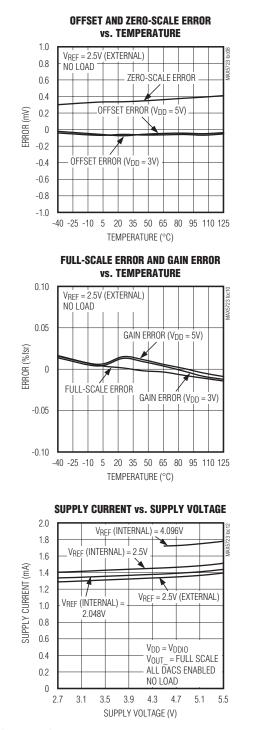


Typical Operating Characteristics

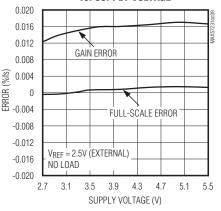
Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

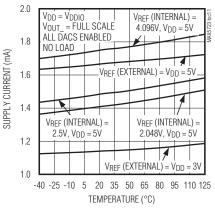
(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)



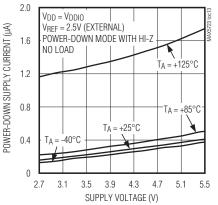
FULL-SCALE ERROR AND GAIN ERROR vs. SUPPLY VOLTAGE



SUPPLY CURRENT vs. TEMPERATURE



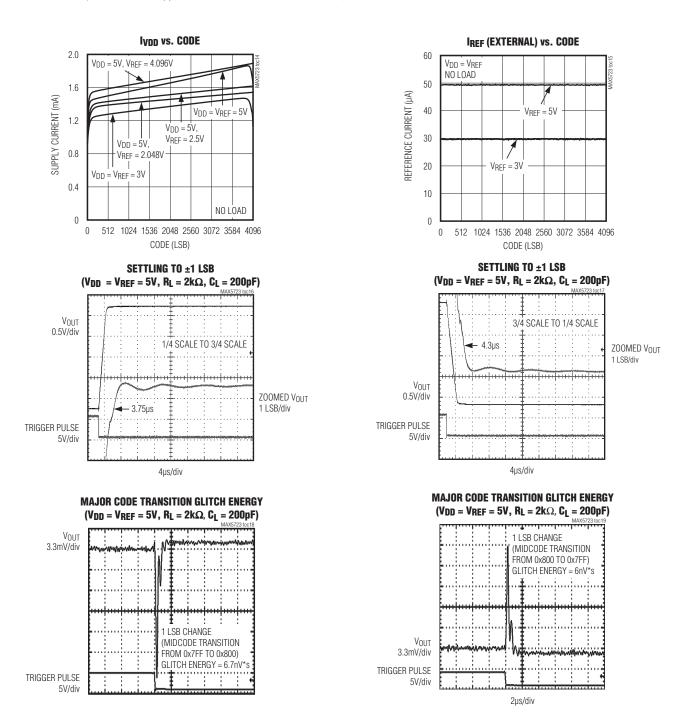
POWER-DOWN MODE SUPPLY CURRENT vs. Supply voltage



Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

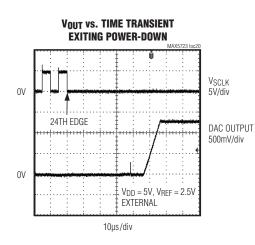
(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)



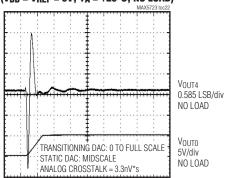
Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

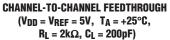
(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)

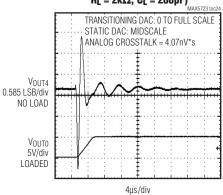


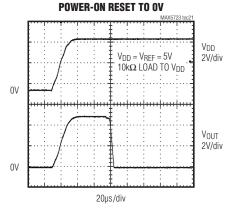
CHANNEL-TO-CHANNEL FEEDTHROUGH (VDD = VREF = 5V, $TA = +25^{\circ}C$, NO LOAD)



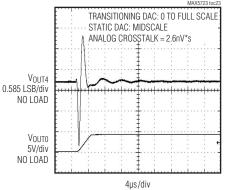
4µs/div



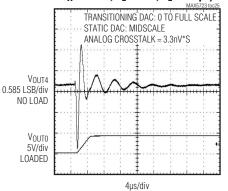




 $\label{eq:channel-to-channel feedthrough} CHANNEL-TO-CHANNEL FEEDTHROUGH (Vdd = 5V, Vref = 4.096V, T_A = +25^{\circ}C, NO LOAD)$



CHANNEL-TO-CHANNEL FEEDTHROUGH (VDD = 5V, VREF = 4.096V (INTERNAL), TA = +25°C, RL = 2k Ω , CL = 200pF)

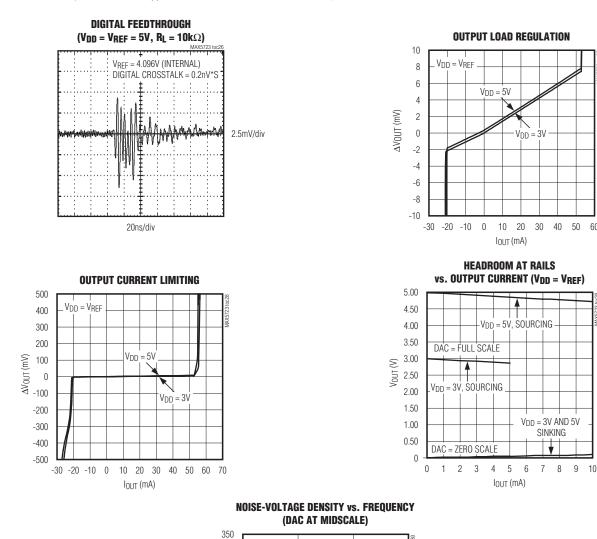


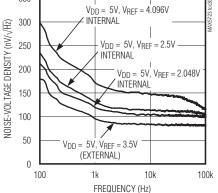
Maxim Integrated

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered **Output DACs with Internal Reference and SPI Interface**

Typical Operating Characteristics (continued)

(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)



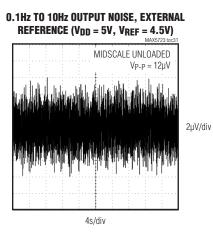


60

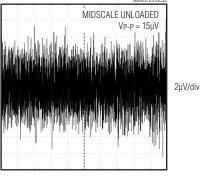
Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)



0.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE (VDD = 5V, VREF = 2.5V)

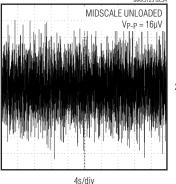


4s/div

O.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE (VDD = 5V, VREF = 2.048V) MISCALE UNLOADED VP-P = 13JV

2µV/div

0.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE (VDD = 5V, VREF = 4.096V)

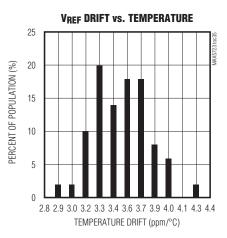


2µV/div

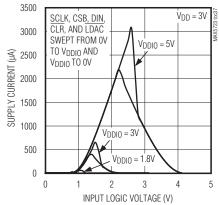
Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

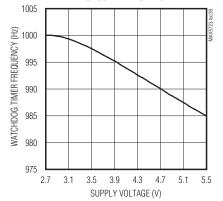
(MAX5725, 12-bit performance, $T_A = +25^{\circ}C$, unless otherwise noted.)

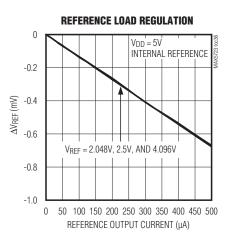


SUPPLY CURRENT vs. SUPPLY VOLTAGE

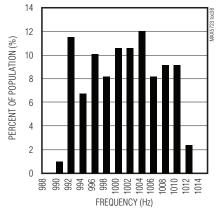




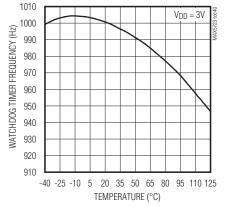




WATCHDOG TIMER PERIOD HISTOGRAM

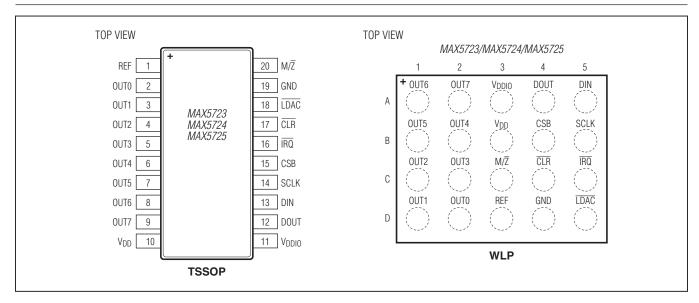


WATCHDOG TIMER FREQUENCY vs. temperature



Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Pin Configurations



Pin Description

	PIN		FUNCTION
TSSOP	WLP	NAME	FUNCTION
1	D3	REF	Reference Voltage Input/Output
2	D2	DAC0	DAC Channel 0 Voltage Output
3	D1	OUT1	DAC Channel 1 Voltage Output
4	C1	OUT2	DAC Channel 2 Voltage Output
5	C2	OUT3	DAC Channel 3 Voltage Output
6	B2	OUT4	DAC Channel 4 Voltage Output
7	B1	OUT5	DAC Channel 5 Voltage Output
8	A1	OUT6	DAC Channel 6 Voltage Output
9	A2	OUT7	DAC Channel 7 Voltage Output
10	B3	V _{DD}	Analog Supply Voltage
11	A3	V _{DDIO}	Digital Supply Voltage
12	A4	DOUT	SPI Serial Data Output
13	A5	DIN	SPI Serial Data Input
14	B5	SCLK	SPI Serial Clock Input
15	B4	CSB	SPI Chip-Select Input
16	C5	ĪRQ	Active-Low Open Drain Interrupt Output. IRQ low indicates watchdog timeout.
17	C4	CLR	Active-Low Asynchronous DAC Clear Input
18	D5	LDAC	Active-Low Asynchronous DAC Load Input
19	D4	GND	Ground
20	C3	M/Z	DAC Output Reset Selection. Connect M/\overline{Z} to GND for zero-scale and connect M/\overline{Z} to V_{DD} for midscale.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Detailed Description

The MAX5723/MAX5724/MAX5725 are 8-channel, lowpower, 8-/10-/12-bit buffered voltage-output DACs. The 2.7V to 5.5V wide supply voltage range and low-power consumption accommodates most low-power and lowvoltage applications. The devices present a $100k\Omega$ load to the external reference. The internal output buffers allow rail-to-rail operation. An internal voltage reference is available with software-selectable options of 2.048V, 2.500V, or 4.096V. The devices feature a fast 4-wire SPI/QSPI/MICROWIRE/DSP-compatible serial interface to save board space and reduce the complexity in isolated applications interface. The MAX5723/MAX5724/ MAX5725 include a serial-in/parallel-out shift register, internal CODE and DAC registers, a power-on-reset (POR) circuit to initialize the DAC outputs to zero scale $(M/\overline{Z} = 0)$ or midscale $(M/\overline{Z} = 1)$, and control logic.

CLR is available to asynchronously clear the DAC outputs to a user-programmable default value, independent of the serial interface. LDAC is available to simultaneously update selected DACs on one or more devices. The MAX5723/MAX5724/MAX5725 also feature user-configurable interface watchdog, with status indicated by the IRQ output.

DAC Outputs (OUT_)

The MAX5723/MAX5724/MAX5725 include internal buffers on all DAC outputs, which provide improved load regulation for the DAC outputs. The output buffers slew at 1V/µs (typ) and drive resistive loads are as low as 2k Ω in parallel with as much as 500pF of capacitance. The analog supply voltage (V_{DD}) determines the maximum output voltage range of the devices since it powers the output buffers. Under no-load conditions, the output buffers drive from GND to V_{DD}, subject to offset and gain errors. With a 2k Ω load to GND, the output buffers drive from GND to vithin 200mV of V_{DD}. With a 2k Ω load to V_{DD}, the output buffers drive from V_{DD} to within 200mV of GND.

The DAC ideal output voltage is defined by:

$$V_{OUT} = V_{REF} \times \frac{D}{2^N}$$

where D = code loaded into the DAC register, V_{REF} = reference voltage, N = resolution.

Internal Register Structure

The user interface is separated from the DAC logic to minimize digital feedthrough. Within the serial interface is an input shift register, the contents of which can be routed to control registers, individual, or multiple DACs as determined by the user command.

Within each DAC channel there is a CODE register followed by a DAC latch register (see the <u>Detailed</u> <u>Functional Diagram</u>). The contents of the CODE register hold pending DAC output settings which can later be loaded into the DAC registers. The CODE register can be updated using both CODE and CODE_LOAD user commands. The contents of the DAC register hold the current DAC output settings. The DAC register can be updated directly from the serial interface using the CODE_LOAD commands or can upload the current contents of the CODE register using LOAD commands or the LDAC logic input.

The contents of both CODE and DAC registers are maintained during power-down states, so that when the DACs are powered on, they return to their previously stored output settings. Any CODE or LOAD commands issued during power-down states continue to update the register contents.

Once the device is powered up, each DAC channel can be independently programmed with a desired RETURN value using the RETURN command. This becomes the value the CODE and DAC registers will use in the event of any watchdog, clear or gate activity, as selected by the DEFAULT command.

Hardware CLR operations and SW_CLEAR commands return the contents of all CODE and DAC registers to their user-selected defaults. SW_RESET commands will reset CODE and DAC register contents to their M/Z selected initial codes. A SW_GATE state can be used to momentarily hold selected DAC outputs in their DEFAULT positions. The contents of CODE and DAC registers can be manipulated by watchdog timer activity, enabling a variety of safety features.

Internal Reference

The MAX5723/MAX5724/MAX5725 include an internal precision voltage reference that is software selectable to be 2.048V, 2.500V, or 4.096V. When an internal reference is selected, that voltage is available on the REF output for other external circuitry (see the <u>Typical Operating</u> <u>Circuits</u>) and can drive loads down to $25k\Omega$.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

External Reference

The external reference input has a typical input impedance of 100k Ω and accepts an input voltage from +1.24V to V_{DD}. Apply an external voltage between REF and GND to use an external reference. The MAX5723/MAX5724/MAX5725 power up and reset to external reference mode. Visit **www.maximintegrated.com/products/references** for a list of available external voltage-reference devices.

M/Z Input

The MAX5723/MAX5724/MAX5725 feature a pin-selectable DAC reset state using the M/Z input. Upon a poweron reset, all CODE and DAC data registers are reset to zero scale (M/Z = GND) or midscale (M/Z = V_{DD}). M/Z is referenced to V_{DD} (not V_{DDIO}). In addition, M/Z must be valid at the time the device is powered up—connect M/Z directly to V_{DD} or GND.

Load DAC (LDAC) Input

The MAX5723/MAX5724/MAX5725 feature an active-low asynchronous LDAC logic input that allows DAC outputs to update simultaneously. Connect LDAC to V_{DDIO} or keep LDAC high during normal operation when the device is controlled only through the serial interface. Drive LDAC low to update the DAC outputs with data from the CODE registers. Holding LDAC low causes the DAC registers to become transparent and CODE data is passed through to the DAC registers immediately updating the DAC outputs. A software CONFIG command can be used to configure the LDAC operation of each DAC independently.

Clear (CLR) Input

The MAX5723/MAX5724/MAX5725 feature an asynchronous active-low $\overline{\text{CLR}}$ logic input that simultaneously sets all selected DAC outputs to their programmable DEFAULT states. Driving $\overline{\text{CLR}}$ low clears the contents of both the CODE and DAC registers and also ignores any on-going SPI command which modifies registers associated with a DAC configured to accept clear operations. To allow a new SPI command, drive $\overline{\text{CLR}}$ high, satisfying the t_{CSC} timing requirement. A software CONFIG com-

Table 1. Format DAC Data Bit Positions

mand can be used to configure the clear operation of each DAC independently.

Watchdog Feature

The MAX5723/MAX5724/MAX5725 feature an interface watchdog timer with programmable timeout duration. This monitors the I/O interface for activity and integrity. If the watchdog is enabled, the host processor must write a valid command to the device within the timeout period to prevent a timeout. If the watchdog is allowed to timeout, selected DAC outputs are returned to the programmable DEFAULT state, protecting the system against control faults.

By default, all watchdog features are disabled; users wishing to activate any watchdog feature must configure the device accordingly. Individual DAC channels can be configured using the CONFIG command to accept the watchdog alarm and to gate, clear, or hold their outputs in response to an alarm. A watchdog refresh event and watchdog behavior upon timeout is defined by a programmable safety level using the WDOG_CONFIG command.

IRQ Output

The MAX5723/MAX5724/MAX5725 feature an active-low open-drain interrupt output indicating to the host when a watchdog timeout has occurred.

Interface Power Supply (V_{DDIO})

The MAX5723/MAX5724/MAX5725 feature a separate supply input (V_{DDIO}) for the digital interface (1.8V to 5.5V). Connect V_{DDIO} to the I/O supply of the host processor.

SPI Serial Interface

The MAX5723/MAX5724/MAX5725 4-wire serial interface is compatible with MICROWIRE, SPI, QSPI, and DSPs. The interface provides three inputs, SCLK, CSB, and DIN. The chip-select input (CSB, active-low) frames the data loaded through the serial data input (DIN). Following a CSB input high-to-low transition, the data is shifted in synchronously and latched into the input register on each falling edge of the serial clock input (SCLK). Each serial operation word is 24-bits long. The DAC data is left justified as shown in <u>Table 1</u>. The serial

PART	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0
MAX5723	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х	Х	Х	Х	Х
MAX5724	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х	Х	Х
MAX5725	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

input register transfers its contents to the destination registers after loading 24 bits of data on the 24th SCLK falling edge. To initiate a new SPI operation, drive CSB high and then low to begin the next operation sequence, being sure to meet all relevant timing requirements. During CSB high periods, SCLK is ignored, allowing communication to other devices on the same bus. SPI operations consisting of more than 24 SCLK cycles are executed on the 24th SCLK falling edge, using the first three bytes of data available. SPI operations consisting of less than 24 SCLK cycles will not be executed. The content of the SPI operation consists of a command byte followed by a two-byte data word.

The DOUT phase for all SPI_READ commands is determined by the readback command used, allowing the selection of the SCLK DOUT update edge best suited to the digital I/O implementation, maximizing data transfer speed and/or timing margin.

Guaranteed non-zero DOUT hold times allow the microprocessor to strobe DOUT on the same edge as the MAX5723/MAX5724/MAX5725 updates for fastest SPI read mode transfers. For example, if DPHA = 0 is used, the MAX5723/MAX5724/MAX5725 update DOUT in response to SCLK falling edges 8-23, while a microprocessor (μ P) with low data hold time requirements can strobe in the DOUT data on SCLK falling edges 9-24. The device supports readback speeds of up to 25MHz for a microprocessor with 5ns data input setup requirements and allowing 35ns for t_{DOT} at V_{DDIO} > 2.7V.

Variable DOUT phase also supports microprocessors with longer data input hold time requirements. For example, if DPHA = 1 is used, the MAX5723/MAX5724/ MAX5725 updates DOUT in response to SCLK rising edges 9-24 while the microprocessor can strobe in the DOUT data on SCLK falling edges 9-24. The device supports readback speeds up to 12.5MHz for a μ P with 5ns data input setup requirements and allowing 35ns for t_{DOT} (assuming 50% duty cycle SCLK).

For improved readback speed while monitoring device status, the SPI_READ_STATUS command repeats the device status information for multiple bits, allowing polling of the device at maximum interface speeds (up to 50MHz when the readback strobe is placed away from DOUT transition edges). This transfer speed cannot be achieved for other forms of readback using the SPI_READ_DATA command, where more DOUT bus transitions occur.

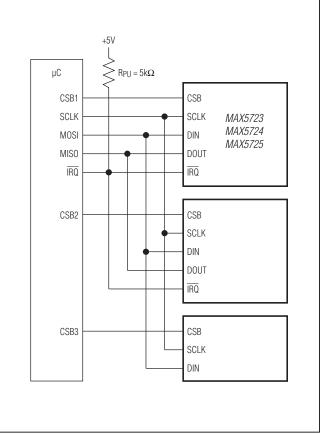


Figure 2. Typical SPI Application Circuit

Figure 1 shows the timing diagram for the complete 4-wire serial interface transmission. The DAC code settings (D) for the MAX5723/MAX5724/MAX5725 are accepted in an offset binary format (see <u>Table 1</u>). Otherwise, the expected data format for each command is listed in <u>Table 2</u>. See <u>Figure 2</u> for an example of a typical SPI circuit application.

SPI User-Command Register Map

This section lists the user-accessible commands and registers for the MAX5723/MAX5724/MAX5725.

Table 2 provides detailed information about the Command Registers.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

COMMAND	B23 E	i i i i i i i i i i i i i i i i i i i	B21	22 B21 B20	320 B19 E		B17	18 B17 B16 E	B 15	B14	B13	B12	B11	B10	B9	B8	B7 E	B6	B5	B4	B3	B2 B1	B0	DESCRIPTION	_
CONFIGURATION AND SOFTWARE COMMANDS	ION AI	ND S(DFTW	ARE (NMOC	IANDS	1		1	-		_	-	_	-	-	-	-	-	-	-	-	-		
DOGW	0	0	0		×	×	×	×			1EOUT	SELE	TIMEOUT SELECTION[11:4]	J[11:4]			SELL	TIMEOUT SELECTION[3:0]	N[3:0]		MD_MASK	Safety Level 00: Low 01: Med 10: High 11: Max	×	Updates watchdog settings and safety levels	
RE	0	0		0	0		REF Mode 00 = EXT 01 = 2.5V 10 = 2.0V 11 = 4.1V	10de EXT 2.5V 2.0V 4.1V	×	×	×	×	×	×	×	×	×	×	×	×	×	× ×	×	Sets the reference operating mode. REF Power (B18): 0 = Internal reference is only powered if at least one DAC is powered if at least one 1 = Internal reference is alwass provered	1
SW_GATE_ CLR	0	0	-	-	0	0	0	0	-	0	0	-	0	-	-	0	0	0	-		0	0	0	Ì	
SW_GATE_ SET	0	0	-	-	0	0	0	-	-	0	0	-	0	-	-	0	0	0	-	-	0	0	0	Initiates a GATE condition	
WD_REFRESH	0	0	-		0	0	-	0	-	0	0	-	0	-	-	0	0	0	-		0	0	0	Refreshes the watchdog timer	
WD_RESET	0	0	-	-	0	0	-	-	-	0	0	-	0		-	0	0	0			0	0	0	Reset the watchdog time out alarm status and refreshes the watchdog timer	,
SW_CLEAR	0	0	-	-	0	-	0	0	-	0	0	-	0	-	-	0	0	0	-		0	0	0	Executes a software clear (all CODE and DAC registers cleared to their DEFAULT values)	
SW_RESET	0	0	-	-	0	-	0	-	-	0	0	-	0	-	-	0	0	0			0	0	0		· · · · · · · · · · · · · · · · · · ·
CONFIG	0		0	-	0	0	0	0	DAC7	DAC6	DAC5	DAC4	DAC3	DAC2	PAC1	DAC0	WDOG Config. 00: DIS 01: GATE 10: CLR 11: HOLD	LD H H S G	GATE_ENB	LDAC_ENB	CLEAR_ENB	~ ×	× ×	Configures selected DAC Watchdog, GATE, LOAD, and CLEAR operations. DACs selected with a 1 in the corresponding DACn bit are updated, DACs with a 0 in the corresponding DACn bit are not impacted)	

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

		ji.	a žr D				SI			
	DESCRIPTION	Sets the Power Mode of the selected DACs (DACs selected with a 1 in the corresponding DACn bit are updated, DACs with a 0 in the corresponding DACn bit are not impacted)	Sets the DEFAULT code settings for selected DACs. Note, DACs in RETURN mode programmable RETURN codes. (DACs selected with a 1 in the corresponding DACn bit are updated, DACs with a 0 in the corresponding DACn bit are not impacted)		Writes data to the selected RETURN register(s)	Writes data to the selected CODE register(s)	Transfers data from the selected CODE registers to the selected DAC register(s)	Simultaneously writes data to the selected CODE register(s) while updating all DAC registers	Simultaneously writes data to the selected CODE register(s) while updating selected DAC register(s)	Writes data to all CODE registers
	B	×			×	×	×	×	×	×
	8	×			×	×	×	×	×	×
	B 2	×			×	×	×	×	×	×
	B3	×			×	×	×	×	×	×
	B 4	×			STER	Ë	×	Ш	E	E
	B5	×	tlues: ID URN Effect		JRN REGIS DATA[3:0]	DE REGISI DATA[3:0]	×	DE REGIST DATA[3:0]	DE REGIS1 DATA[3:0]	DE REGISI DATA[3:0]
	B6	Power Mode 00 = 01 = 01 = 10 = PD 100kΩ 11 = PD Hi-Z	Default Values: 000: MZ 001: ZERO 010: MID 011: FULL 100: RETURN 101+: No Effect		RETURN REGISTER DATA[3:0]	CODE REGISTER DATA[3:0]	×	CODE REGISTER DATA[3:0]	CODE REGISTER DATA[3:0]	CODE REGISTER DATA[3:0]
	B7	л о о о о о о с с с т т	Defi 00 101-101			ŏ	×	ŏ	Ŭ	ŏ
	B8	DACO	DACO				×			
	B9	DAC1	DAC1	-			×			
	B10	DAC2	DAC2		STER	Ë _	×		LER	Ë _
(B11	DAC3	DAC3		RETURN REGISTER DATA[11:4]	CODE REGISTER DATA[11:4]	×	CODE REGISTER DATA[11:4]	CODE REGISTER DATA[11:4]	CODE REGISTER DATA[11:4]
ned	B12	DAC4	DAC4		IURN DATA	DATA	×	DDE R DATA	DDE R DAT#	DDE R DATA
tin	B13	DAC5	DAC5		BEI	ŏ	×	ŏ	ŏ	ŏ
Son	B14	DAC6	DAC6				×			
y (c	B15	DAC7	DAC7				×			
nar	B16	0	0			E	E		c	0
Summary (continued)	B17	0	0		ectio	ectio	ectio	ectio	ectio	0
່ Sເ	B18	0	0		DAC Selection	DAC Selection	DAC Selection	DAC Selection	DAC Selection	0
ands	B19	0	0	1						0
ma	B21 B20	0	0		-	0	.	0	-	0
mo	B21	0	1		-	0	0	-	-	0
Ŭ	B22	-	-		-	0	0	0	0	-
SP	B23	0	0	SDN	0	-	-	-	-	-
Table 2. SPI Comm	COMMAND	POWER	DEFAULT	DAC COMMANDS	RETURNn	CODEn	LOADn	CODEn_ LOAD_ALL	CODEn_ LOADn	CODE_ALL

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

)	2		5)			-)))														
COMMAND	B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2 E	B1 B0	DESCRIPTION
LOAD_ALL	-	-	0	0	0	0	0	-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	Updates all DAC latches with current CODE register data
CODE_ALL LOAD_ALL	-	-	0	0	0	0	-	0			00	DE REGIST DATA[11:4]	CODE REGISTER DATA[11:4]	с.			COL	DE REGISI DATA[3:0]	CODE REGISTER DATA[3:0]		~ ×	×	× ×	Simultaneously writes data to the all CODE registers while updating all DAC registers
RETURN_ALL		-	0	0	0	0	-	-			RET	URN REGIS DATA[11:4]	RETURN REGISTER DATA[11:4]	EB			RETU	JRN REGIS DATA[3:0]	RETURN REGISTER DATA[3:0]	E	×	×	×	Writes data to all RETURN registers
SPI_DATA_ REQUEST	-	-	0	-	_	DACS	DAC Selection	ç	0 Z		DATA SEL [1:0] 00 = DAC 01 = CODE 10 = RET 11 = WDT	11:0]	×	×	×	×	×	×	×	×	~ ×	×	× ×	Setup data request for readback. INC indicates if the DAC selection is incremented to the next DAC after each SPI_READ_DATA operation DATA SEL[1:0] indicates the data content to be read back
SPI_READ	-	-	-	0	0	0	×	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	DPHA = 0 Readback status
STATUS	-	.	-	0	0	-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	DPHA = 1 Readback status
SPI_READ	-	-	-	0		0	×	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	DPHA = 0 Readback requested data
DATA	-	-	-	0		-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	DPHA = 1 Readback requested data
NO OPERATION COMMANDS	ON CO	MMM	SON																					
	-	-	0	0	0		\times	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	
No Operation	-	-	0	0	-	0	×	Х	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	have no effect on the device, but will refresh the watchdor timer if
	-	-	0	0	-	-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	~ ×	×	× ×	
Reserved Commands: Any commands not specifically listed above are reserved for Maxim internal use only.	nmanc	Js: Ar	Jy corr	mand	s not	specifi	cally li	sted al	bove	are res	erved	for Ma:	×im int	ernal u	ise onl		1	1	1	1	-		-	-

Table 2. SPI Commands Summary (continued)

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

RETURNn Command

The RETURN command (B[23:20] = 0111) sets the programmable default RETURN value. This value is used for all future watchdog, clear, and gate operations when RET is selected for the DAC using the DEFAULT command. Issuing this command with DAC_ADDRESS set to all DACs will program the value for all RETURN registers and is equivalent to RETURN_ALL. **Note:** This command is inaccessible when a watchdog timeout has occurred if the watchdog timer is configured for safety level = high or max.

CODEn Command

The CODEn command (B[23:20] = 1000) updates the CODE register contents for the selected DAC(s). Changes to the CODE register content based on this command will not affect DAC outputs directly unless the LDAC input is in a low state or the DAC latch has been configured as transparent using the CONFIG command. Issuing this command with DAC_ADDRESS set to all DACs will program the value for all CODE registers and is equivalent to CODE_ALL.

LOADn Command The LOADn command (B[23:20] = 1001) updates the DAC register content for the selected DAC(s) by uploading the current contents of the selected CODE register(s) into the selected DAC register(s). Channels for which CODE content has not been modified since the last LOAD or LDAC operation will not be updated to reduce digital crosstalk. Issuing this command with DAC_ADDRESS set to all DACs will update the contents of all DAC registers and is equivalent to LOAD_ALL.

CODEn_LOADn Command

The CODEn_LOADn command (B[23:20] = 1011) updates the CODE register contents for the selected DAC(s) as well as the DAC register content of the selected DAC(s). Channels for which CODE content has not been modified since the last LOAD or $\overline{\text{LDAC}}$ operation will not be updated to reduce digital crosstalk. Issuing this command with DAC_ADDRESS set to all DACs is equivalent to the CODE_ALL_LOAD_ALL (B[23:16] = 1100_0010) command.

CODEn_LOAD_ALL Command

The CODEn_LOAD_ALL command (B[23:20] = 1010) updates the CODE register contents for the selected DAC(s) as well as the DAC register content of all DACs. Channels for which CODE content has not been modified since the last LOAD or LDAC operation will not be updated to reduce digital crosstalk. Issuing this command with

Table 3. DAC Selection

B19	B18	B17	B16	DAC SELECTED
0	0	0	0	DACO
0	0	0	1	DAC1
0	0	1	0	DAC2
0	0	1	1	DAC3
0	1	0	0	DAC4
0	1	0	1	DAC5
0	1	1	0	DAC6
0	1	1	1	DAC7
1	Х	Х	Х	ALL DACs

DAC_ADDRESS set to all DACs will update the CODE and DAC register contents of all DACs and is equivalent to CODE_ALL_LOAD_ALL. Note this command by definition will modify at least one CODE register; to avoid this use the LOAD command with DAC_ADDRESS set to all DACs or the LOAD_ALL command.

CODE_ALL Command

The CODE_ALL command $(B[23:16] = 1100_0000)$ updates the CODE register contents for all DACs.

LOAD_ALL Command

The LOAD_ALL command (B[23:16] = $1100_{-}0001$) updates the DAC register content for all DACs by uploading the current contents of the CODE registers to the DAC registers.

CODE_ALL_LOAD_ALL Command

The CODE_ALL_LOAD_ALL command (B[23:16] = 1100_{0010}) updates the CODE register contents for all DACs as well as the DAC register content of all DACs.

RETURN_ALL Command

The RETURN_ALL command ($B[23:16] = 1100_{0011}$) updates the RETURN register contents for all DACs.

NO_OP Commands Command

All unused commands in the space (B[23:16] = 1100_01XX or 1100_1XXX) have no effect on the device, but will refresh the watchdog timer (if active) with the safety level set to low.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

WDOG Command

The WDOG command (B[23:20] = 0001) updates the watchdog timeout settings and safety levels for the device. Timeout thresholds are selected in 1ms increments (1ms to 4095ms are available). The WD_MASK bit can be used to mask the IRQ operation in response to the watchdog status, if WD_MASK = 1, watchdog alarms will not assert IRQ. The watchdog alarm status (WD bit) can be polled using the available SPI status readback commands regardless of WD_MASK settings. A write to this register will not reset a previously triggered watchdog alarm (use the WD_RESET command for this purpose). The watchdog timer refresh and timeout behavior is defined by the programmable safety level below.

Available safety levels (WL[1:0]):

Low (00): Watchdog timer will refresh with the execution of any valid user mode command or no-op. Any successful slave address acknowledge qualifies to restart the watchdog timer (run to the ninth SCL edge), regardless of the command which follows. Issuing hardware CLR or LDAC falling edge will also refresh the watchdog timer. A triggered watchdog alarm does not prevent writes to

Table 4. WDOG Command Format

any register. LDAC and CLR inputs still function after a watchdog timeout event.

Medium (01): A WD_REFRESH command must be executed in order to refresh the watchdog timer. Other commands as well as LDAC or CLR activity do not refresh the watchdog timer. A triggered watchdog alarm does not prevent writes to any register. LDAC and CLR inputs still function after a watchdog timeout event.

High (10): A WD_REFRESH command must be executed to refresh the watchdog timer. Other commands as well as LDAC or CLR activity do not refresh the watchdog timer. A triggered watchdog alarm prevents execution of all POWER, REF, CONFIG, DEFAULT, and RETURN commands. LDAC and CLR inputs still function after a watchdog timeout event.

Max (11): A WD_REFRESH command must be executed to refresh the watchdog timer. Other commands, as well as <u>LDAC</u> or <u>CLR</u> activity, do not refresh the watchdog timer. A triggered watchdog alarm prevents execution of all POWER, REF, CONFIG, DEFAULT, and RETURN commands. <u>LDAC</u> and <u>CLR</u> are gated and do not function after a watchdog timeout event.

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B8	B7	B 6	B 5	B 4	B3	B2	B1	B0
0	0	0	1	Х	Х	X	Х	C11	C10	C9	C8	C 7	C6	C 5	C4	C3	C2	C1	C0	WDM	WL1	WL0	Х
WD	IOG C	omm	and		Don't	Care				Tim	eout	Select	ion			Tim	eout \$	Selec	tion	WD_MASK	00: 0 M	ety vel: Low 1: ed 0: gh	Don't Care
		De	fault	Value	\rightarrow			0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	Х
		Default Value → Command Byte							Da	ata Hi	gh By	te					D	ata L	ow By	te			

Table 5. Watchdog Safety Level Protection

WATCHDOG SAFETY LEVEL	ANY COMMAND REFRESHES WDT	CLR/LDAC REFRESHES WDT	SW_RESET PLUS WD_RFRS REFRESHES WDT	ALL REGISTERS ACCESSIBLE AFTER WDT TIMEOUT*	CLR/LDAC AFFECT DAC REGISTERS AFTER WDT TIMEOUT*
00 (Low)	Х	Х	Х	Х	Х
01 (Med)	—	—	Х	Х	Х
10 (High)	—	—	Х	—	Х
11 (Max)	—	_	Х	_	_

*Unless otherwise affected by Watchdog HOLD or CLR configurations as set by the CONFIG command. See the CONFIG register definition for details.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

REF Command

The REF command (B[23:20] = 0010) updates the global reference setting used for all DAC channels. If an internal reference mode is selected, bit RF2 (B18) defines the reference power mode. If RF2 is set to zero (default), the reference will be powered down any time all DAC channels are powered down (i.e. the device is in STANDBY mode). If RF2 is set to one, the reference will remain powered even if all DAC channels are powered down, allowing continued operation of external circuitry (note in this mode the low current shutdown state is not available). This command is inaccessible when a watchdog timeout has occurred and the watchdog time is configured with a safety level of high or max.

SW_GATE_CLR Command

The SW_GATE_CLR command (B[23:0] = 0011_0000_ 1001_0110_0011_0000) will remove any existing GATE condition initiated by a previous SW_GATE_SET comand.

SW_GATE_SET Command

The SW_GATE_SET command (B[23:0] = $0011_0001_1001_0110_0011_0000$) will initiate a GATE condition. Any DACs configured with GTB = 0 (see the <u>CONFIG</u> <u>Command</u> section) will have their outputs held at the selected DEFAULT value until the GATE condition is later removed by a subsequent SW_GATE_CLR command. While in gate mode, the CODE and DAC registers continue to function normally and are not reset (unless reset by a watchdog timeout).

WD_REFRESH Command

The WD_REFRESH command (B[23:0] = $0011_001_$ 1001_0110_0011_0000) will refresh the watchdog timer. This is the only command which will refresh the watchdog timer if the device is configured with a safety level of medium, high, or max. Use this command to prevent the watchdog timer from timing out.

WD_RESET Command

A WD_RESET command (B[23:0] = $0011_0011_1001_011_0001_0000$) will reset the watchdog interrupt (timeout) status and refresh the watchdog timer. Use this command to reset the IRQ timeout condition after the watchdog timer has timed out. Any DACs impacted by an existing timeout condition will return to normal operation.

SW_CLEAR Command

A software clear command (B[23:0] = $0011_0100_01_0110_0011_0000$) will clear the contents of the CODE and DAC registers to the DEFAULT state for all channels configured with CLB = 0 (see CONFIG command).

SW_RESET Command

A software reset command (B[23:0] = 0011_0101_ 1001_0110_0011_0000) will reset all CODE, DAC, and configuration registers to their defaults (including POWER, DEFAULT, CONFIG, WDOG, and REF registers), simulating a power-on reset.

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B 8	B 7	B 6	B 5	B 4	B 3	B2	B1	B0
0	0	1	0	0	RF2	RF1	RF0	X	Х	X	Х	Х	Х	Х	Х	X	Х	X	X	Х	X	Χ	Х
R	EF Co	omma	nd	Reserved	0 = DAC Controlled 1 = Always ON	00: 01: 10:	Mode: EXT 2.5V 2.0V 4.0V				Don't	Care						C	Don't	Care	1		
	Defa	ult Va	$lue \rightarrow$		0	0	0	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	X	Х	Х
			Comr	mand	Byte					D	ata Hi	gh By	te					Da	ta Lo	w By	rte		

Table 6. REF Command Format

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

POWER Command

The POWER command (B[23:20] = 0100) updates the power mode settings of the selected DACs. DACs that are not selected do not update their power settings in response to the command. The new power setting is determined by bits PD[1:0] (B[7:6]) while the affected DAC(s) are selected using B[15:8]). If all DACs are powered down and the RF2 bit is not set, the device enters a STANDBY mode (all analog circuitry is disabled). This command is inaccessible when a watchdog timeout has

occurred and the watchdog timer is configured with a safety level of high or max.

Available power modes (PD[1:0]):

Normal (00): DAC channel is active (default).

PD 1k Ω (01): Power down with 1k Ω termination to GND. PD 100k Ω (10): Power down with 100k Ω termination to GND.

PD Hi-Z (11): Power down with high-impedance output.

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B8	B7	B 6	B 5	B 4	B 3	B2	B1	B0
0	1	0	0	0	0	0	0	7	6	5	4	3	2	1	0	PD1	PD0	X	Х	Х	Х	Χ	Χ
PO'	WER C	Comma	and		Rese	erved			1	Multip	le DA	C Sel	ectior	١			de: = mal 1kΩ =)kΩ		C	Don't	Care		
		De	efault \	Value	\rightarrow						0	0	Х	Х	Х	Х	Х	Х					
		С	omma	nd By	te			Data High Byte								Dat	a Lov	v Byte	9				

Table 7. POWER Command Format

CONFIG Command

The CONFIG command (B[23:16] = 0101) updates the watchdog, gate, load, and clear mode settings of the selected DACs. DACs which are not selected do not update their settings in response to the command. The new mode settings to be written are determined by bits B[7:3] while the affected DAC(s) are selected by B[15:8]. This command is inaccessible when a watchdog timeout has occurred and the watchdog timer is configured with a safety level of high or max.

Watchdog Configuration:

WDOG Config settings are written by WC[1:0] (B[7:6]):

DISABLE (WC = 00): Watchdog timeout does not affect the operation of the selected DAC.

GATE (WC = 01): DAC code is gated to DEFAULT value in response to watchdog timeouts. Unless otherwise prohibited by the watchdog safety level, $\overline{\text{LDAC}}$, $\overline{\text{CLR}}$,

and write operations to the CODE and DAC registers are accepted but will not be reflected on the DAC output until the watchdog timeout status is reset.

 $\overline{\text{CLR}}$ (WC = 10): CODE and DAC register contents are cleared to DEFAULT value in response to watchdog timeouts. All writes to CODE and DAC registers are ignored and $\overline{\text{LDAC}}$ or $\overline{\text{CLR}}$ input activity has no effect until the watchdog timeout status is reset, regardless of watchdog safety level.

HOLD (WC = 11): DAC code is held at its previously programmed value in response to watchdog timeout. All writes to DAC and CODE registers are ignored and $\overline{\text{LDAC}}$ or $\overline{\text{CLR}}$ input activity has no effect until the watchdog timeout status is reset, regardless of watchdog safety level.

Note: For the watchdog to timeout and have an impact, the function must first be enabled and configured using the WDOG command.

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Gate Configuration:

The DAC GATE setting is written by GTB (B5); GATE operation is as follows:

GTB = 0: Enables software gating function (default), DAC outputs are gated to their DEFAULT settings as long as the device remains in GATE mode (set by SW_GATE_SET and removed by SW_GATE_CLR).

GTB = 1: Disable software gating function, DAC outputs are not impacted by GATE mode.

Load Configuration:

The LDAC_ENB setting is written by LDB (B4); LDAC_ENB operation is as follows:

LDB = 0: DAC latch is operational, enabling $\overline{\text{LDAC}}$ and LOAD functions (default).

LDB = 1: DAC latch is transparent, the CODE register content controls the DAC output directly.

Clear Configuration:

CLEAR_ENB setting is written by CLB (B3); CLEAR_ENB operation is as follows:

CLB = 0: Clear input and command functions impact the DAC (default), clearing CODE and DAC registers to their DEFAULT value.

CLB = 1: Clear input and command functions have no effect on the DAC.

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B 8	B7	B6	B5	B4	B3	B2	B1	B0
0	1	0	1	0	0	0	0	7	6	5	4	3	2	1	0	WC1	WC0	GTB	LDB	CLB	Х	Х	Х
CON	IFIG (Comm	nand		Rese	erved			ſ	Multip	le DA	.C Sel	ectior	1		Cor 0 DISA 01: 0 10:	~	GATE_ENB	LDAC_ENB	CLEAR_ENB	Do	n't Ca	are
		De	fault	Value	\rightarrow			1	1	1	1	1	1	1	1	0	0	0	0	0	Х	Х	Х
		Со	mma	nd B	yte				Data High Byte						D	ata Lov	w Byte						

Table 8. CONFIG Command Format

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

DEFAULT Command

The DEFAULT command (B[23:20] = 0110) selects the default value for selected DACs. DACs which are not selected do not update their default settings in response to the command. These default values are used for all future watchdog, clear, and gate operations. The new default setting is determined by bits DF[2:0] (B[7:5]) while the affected DAC(s) are selected using B[15:8]. This command is inaccessible when a watchdog timeout has occurred and the watchdog timer is configured with a safety level of high or max. Note the selected default values do not apply to resets initiated by SW_RESET commands or supply cycling, both of which return all

DACs to the values determined by the M/\overline{Z} input and reset this register to M/\overline{Z} mode.

Available default values (DF[2:0]):

 M/\overline{Z} (000): DAC channel defaults to value as selected by the M/\overline{Z} input (default).

ZERO (001): DAC channel defaults to zero scale.

MID (010): DAC channel defaults to midscale.

FULL (011): DAC channel defaults to full scale.

RETURN (100): DAC channel defaults to the value programmed by the RETURN command.

No Effect (101, 110, 111): DAC channel default behavior is unchanged.

Table 9. DEFAULT Command Format

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B 8	B7	B6	B5	B4	B 3	B2	B1	B0
0	1	1	0	0	0	0	0	7	6	5	4	3	2	1	0	DF2	DF1	DF0	Х	Х	Х	Х	Х
DEFA	AULT	Comr	nand		Rese	erved				Multip	le DA	C Sel	ectior	I		00 00 01 100:	ult Va 00: M/ 1: ZEF 10: MI 1: FU : RETU : No E	IZ RO D LL		Do	n't Ca	are	
		De	fault	Value	\rightarrow			1	1	1	1	1	1	1	1	0	0	0	Х	Х	Х	Х	Х
		Сс	mma	nd By	/te				Data High Byte							Da	ata Lo	w Byt	е				

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

SPI_DATA_REQUEST Command

The SPI_DATA_REQUEST command (B[23:20] = 1101) sets up the data request for future SPI_READ_DATA operations. SPI_READ_DATA is used to fetch the current settings of the internal CODE, DAC, or RETURN registers for each channel or the watchdog configuration (WDOG) settings or the device. The DAC address provided tells the part which channel location data is to be read back by the next SPI_READ_DATA command (see Table 3). Setting the DAC address greater than the number of available DACS will read back channel 0 content.

The INC bit tells the device how the next readback will update the DAC address pointer:

0 = Fix the address pointer (all further readbacks continue at the current address).

1 = Increment the address pointer (further readbacks continue at the next address, with rollover, default).

The SEL[1:0] bits tells the part what type of data is requested:

DAC (00): DAC register data (current DAC latch data, not subject to gating status, default).

CODE (01): CODE register data.

RET (10): RETURN register data.

WDT (11): WDOG register data (DAC selection does not apply).

Table 10. SPI_DATA_REQUEST Command Format

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B 6	B5	B 4	B 3	B2	B1	B0
1	1	0	1	DA	C SEL	ECTI	ON	INC	SEL	[1:0]	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
SPI_I	DATA_	_REQI	UEST	D	AC Se	electio	on	Increment	Sele 00: [01: C 10:	ata ction DAC ODE RET WDT		Do	n't Ca	re					Don't	Care			
De	efault \	Value	\rightarrow	0	0	0	0	1	0	0	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
		Сс	omma	nd By	te					Da	ata Hi	gh By	te					D	ata Lo	ow By	te		

SPI_READ_STATUS Command

The SPI_READ_STATUS command (B[23:18] = 111000 for DPHA = 0, B[23:18] = 111001 for DPHA = 1) reads back the watchdog timer and CLR pin status (intentionally repeated to allow maximum interface speeds) through DOUT.

DIN[18] selects the DOUT Phase (DPHA) to be used (see the SPI Serial Interface Timing Diagram in Figure 1 for details).

WD_STAT indicates a watchdog timeout condition. It reads 0 during normal operation, 1 during a timeout. WD_STAT is not masked by the WD_MASK bit in the WDOG_CONFIG command.

 $\overline{\text{CLR}}$ _STAT indicates the line level of the $\overline{\text{CLR}}$ pin. '0' indicates the $\overline{\text{CLR}}$ input is or was asserted (grounded) during the current SPI operation. '1' indicates the $\overline{\text{CLR}}$ input is not currently asserted (V_{DDIO} level).

Table 11. SPI_READ_STATUS Command Format

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B 9	B8	B7	B 6	B5	B 4	B 3	B2	B1	В0
1	1	1	0	0	0	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
	SPI_I	READ	_STA	TUS (I	DPHA	(= 0)			DOL	JT = V	VD_S	TAT (f	Repea	ited)			DOU	$T = \overline{C}$	ELR_S	TAT (Repe	ated)	
1	1	1	0	0	1	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
	11001XX SPI_READ_STATUS (DPHA = 1)							DOL	JT = V	VD_S	TAT (f	Repea	ited)			DOU	$T = \overline{C}$	ER_S	TAT (Repe	ated)		
		С	omma	ind By	/te					Da	ata Hi	gh By	rte					D	ata Lo	ow By	te		

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

SPI_READ_DATA Command

The SPI_READ_DATA command (B[23:18] = 111010 for DPHA = 0, B[23:18] = 111011 for DPHA = 1) reads back the data requested using the SPI_DATA_REQUEST command through DOUT.

DIN[18] selects the DOUT phase (DPHA) to be used (see <u>Figure 1</u> for details, and the SPI Timing Characteristics in the <u>Electrical Characteristics</u> for a complete listing of

readback speed capabilities based on the DPHA selection).

The SPI_READ_DATA command provides register and address data as defined by the SPI_DATA_REQUEST configuration SEL bits. SPI_READ_DATA also increments the channel address pointer if configured to do so by the SPI_DATA_REQUEST INC bit, the address readback is the address corresponding to the data returned.

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B 8	B7	B 6	B5	B 4	B 3	B2	B1	B0
1	1	1	0	1	0	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
SPI	_REA	D_DA	TA (C	PHA	= 0, S	SEL =	00)			DOL	JT = C	DAC[1	1:4]			DOI	JT =	DAC[3:0]	AI	DDRE	SS[3:	0]
SPI	_REA	D_DA	TA (C	PHA	= 0, S	SEL =	01)			DOU	T = C	ODE[11:4]			DOU	IT = C	ODE	[3:0]	AI	DDRE	SS[3:	0]
SPI	_REA	D_DA	TA (C	PHA	= 0, S	SEL =	10)	DOUT = RETUR			TURN	I[11:4]]		DO	UT =	RET[3	3:0]	AI	DDRE	SS[3:	0]	
SPI	_REA	D_DA	TA (C	PHA	= 0, S	SEL =	11)	1) DOUT = WDOG[15:8] DOUT = WDOG[7				OG[7:	1]		0								
1	1	1	0	1	1	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
SPI	_REA	D_DA	TA (C	PHA	= 1, S	SEL =	00)			DOL	JT = C	DAC[1	1:4]			DOI	JT =	DAC[3:0]	AI	DDRE	SS[3:	0]
SPI	_REA	D_DA	TA (C	PHA	= 1, S	SEL =	01)			DOU	T = C	ODE[11:4]			DOU	IT = C	ODE	[3:0]	AI	DDRE	SS[3:	0]
SPI	_REA	D_DA	TA (C	PHA	= 1, S	SEL =	10)		۵	DOUT	= RE	TURN	I[11:4]]		DO	UT =	RET[3	3:0]	AI	DDRE	SS[3:	0]
SPI	_REA	D_DA	TA (C	PHA	= 1, S	SEL =	11)			DOU	Γ = W	DOG[15:8]				D	= TUC	= WD	OG[7:	1]		0
	Command Byte							Da	ata Hi	gh By	te					D	ata Lo	ow By	te				

Table 12. SPI_READ_DATA Command Format

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Applications Information

Power-On Reset (POR)

When power is applied to V_{DD} and V_{DDIO} , the DAC output is set to zero scale. To optimize DAC linearity, wait until the supplies have settled and the internal setup and calibration sequence completes (200µs, typ).

Power Supplies and Bypassing Considerations

Bypass V_{DD} and V_{DDIO} with high-quality ceramic capacitors to a low-impedance ground as close as possible to the device. Minimize lead lengths to reduce lead inductance. Connect the GND to the analog ground plane.

Layout Considerations

Digital and AC transient signals on GND can create noise at the output. Connect GND to form the star ground for the DAC system. Refer remote DAC loads to this system ground for the best possible performance. Use proper grounding techniques, such as a multilayer board with a low-inductance ground plane, or star connect all ground return paths back to the MAX5723/MAX5724/MAX5725 GND. Carefully layout the traces between channels to reduce AC cross-coupling. Do not use wire-wrapped boards and sockets. Use shielding to minimize noise immunity. Do not run analog and digital signals parallel to one another, especially clock signals. Avoid routing digital lines underneath the MAX5723/MAX5724/MAX5725 package.

Definitions

Integral Nonlinearity (INL)

INL is the deviation of the measured transfer function from a straight line drawn between two codes once offset and gain errors have been nullified.

Differential Nonlinearity (DNL)

DNL is the difference between an actual step height and the ideal value of 1 LSB. If the magnitude of the DNL \leq 1 LSB, the DAC guarantees no missing codes and is monotonic. If the magnitude of the DNL \geq 1 LSB, the DAC output may still be monotonic.

Offset error indicates how well the actual transfer function matches the ideal transfer function. The offset error is calculated from two measurements near zero code and near maximum code.

Gain Error

Offset Error

Gain error is the difference between the ideal and the actual full-scale output voltage on the transfer curve, after nullifying the offset error. This error alters the slope of the transfer function and corresponds to the same percentage error in each step.

Zero-Scale Error

Zero-scale error is the difference between the DAC output voltage when set to code zero and ground. This includes offset and other die level nonidealities.

Full-Scale Error

Full-scale error is the difference between the DAC output voltage when set to full scale and the reference voltage. This includes offset, gain error, and other die level nonidealities.

Settling Time

The settling time is the amount of time required from the start of a transition, until the DAC output settles to the new output value within the converter's specified accuracy.

Digital Feedthrough

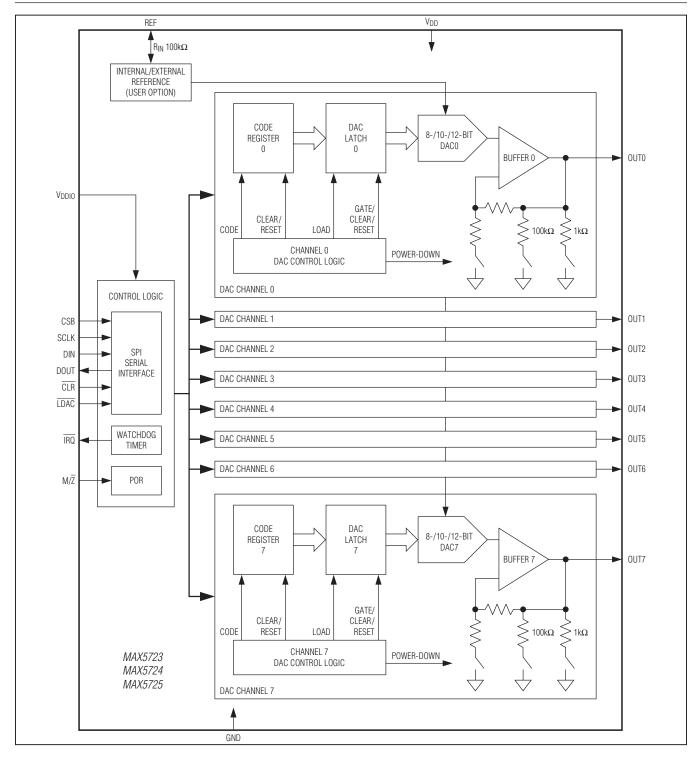
Digital feedthrough is the amount of noise that appears on the DAC output when the DAC digital control lines are toggled.

Digital-to-Analog Glitch Impulse

A major carry transition occurs at the midscale point where the MSB changes from low to high and all other bits change from high to low, or where the MSB changes from high to low and all other bits change from low to high. The duration of the magnitude of the switching glitch during a major carry transition is referred to as the digital-to-analog glitch impulse. Although all bits change, larger steps may lead to larger glitch energy.

The digital-to-analog power-up glitch is the duration of the magnitude of the switching glitch that occurs as the device exits power-down mode.

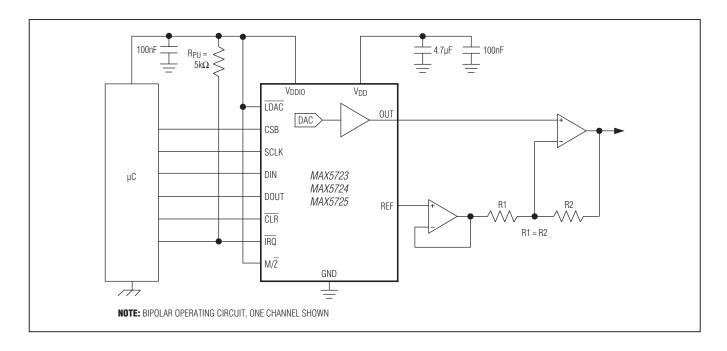
Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

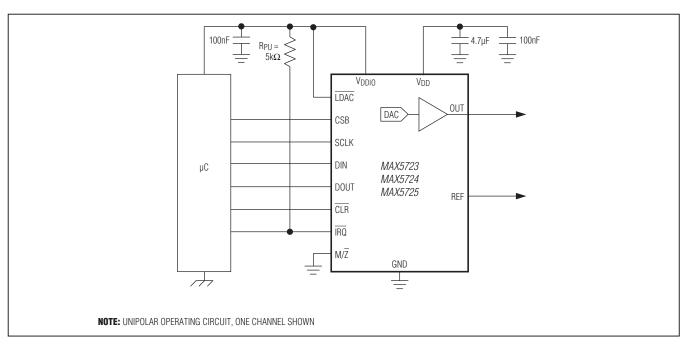


Detailed Functional Diagram

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Circuits





Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	RESOLUTION (BIT)
MAX5723AUP+	-40°C to +125°C	20 TSSOP	8
MAX5724AUP+	-40°C to +125°C	20 TSSOP	10
MAX5725AAUP+	-40°C to +125°C	20 TSSOP	12
MAX5725AWP+T	-40°C to +125°C	20 WLP	12
MAX5725BAUP+	-40°C to +125°C	20 TSSOP	12

Note: All devices are specified over the -40°C to +125°C temperature range.

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

Chip Information

PROCESS: BiCMOS

Package Information

For the latest package outline information and land patterns (footprints), go to <u>www.maximintegrated.com/packages</u>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
20 TSSOP	U20+1	<u>21-0066</u>	<u>90-0116</u>
20 WLP	W202C2+1	<u>21-0059</u>	Refer to Application Note 1891

Ultra-Small, Octal-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	3/12	Initial release	_
1	11/12	Revised the Ordering Information, Electrical Characteristics, Typical Operating Characteristics, Pin Configuration, Pin Description, Figure 1, and the DAC Outputs (OUT_), CODEn_LOADn Command, and Offset Error sections.	3, 5, 8, 10–13, 15–18, 23, 31, 34
2	2/13	Released the MAX5723/MAX5724/MAX5725B. Updated the <i>Electrical Characteristics</i> global and Note 3.	2–8, 34



Maxim Integrated cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim Integrated product. No circuit patent licenses are implied. Maxim Integrated reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.

Maxim Integrated 160 Rio Robles, San Jose, CA 95134 USA 1-408-601-1000

© 2013 Maxim Integrated Products, Inc.

Maxim Integrated and the Maxim Integrated logo are trademarks of Maxim Integrated Products, Inc.

35